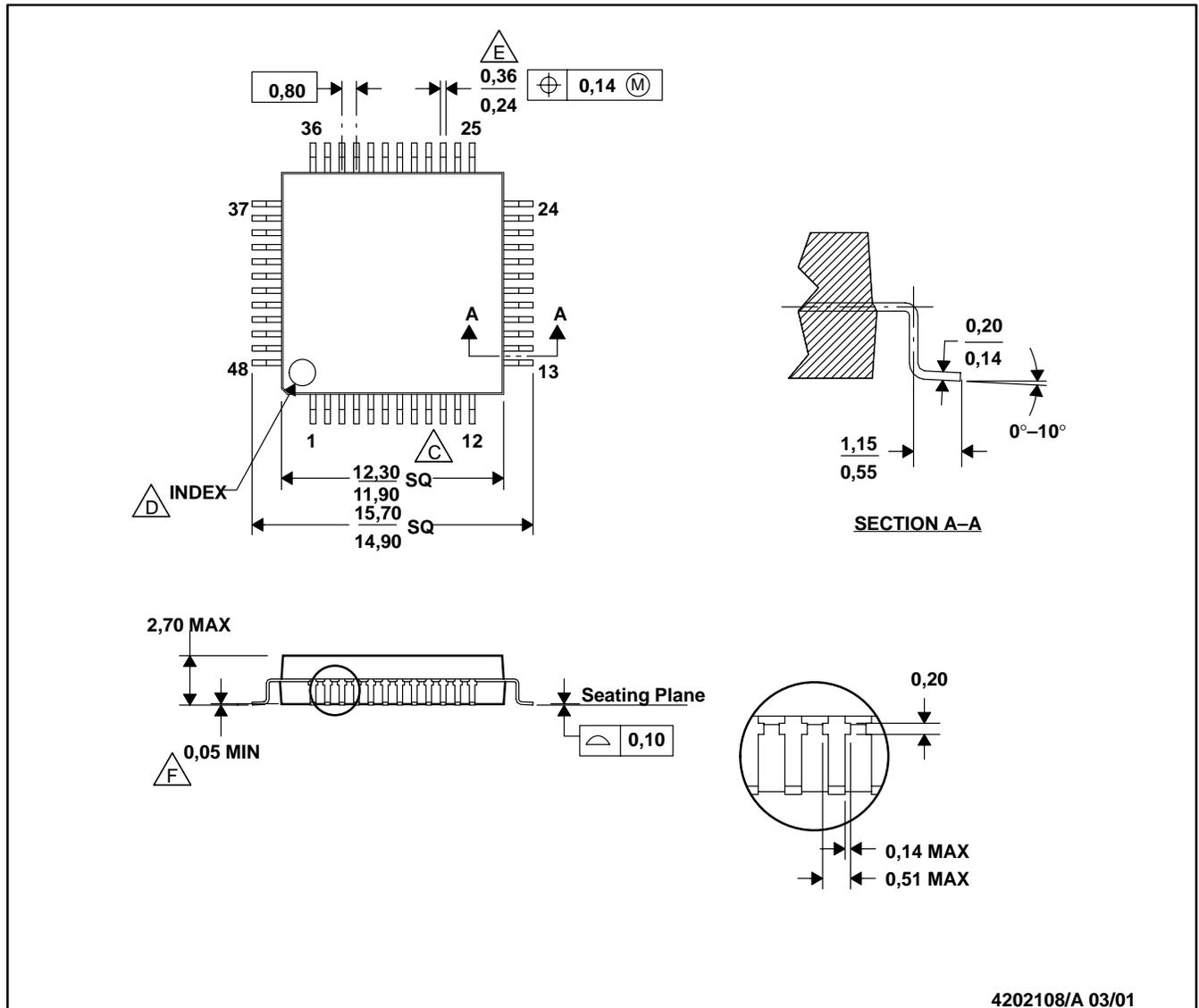


PJS (S-PQFP-G48)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold protrusion. Allowable protrusion is 0,25 mm per side. Dimension is the maximum plastic body dimension including mold mismatch.
 D. Details of pin 1 identifier are optional but must be located within the zone indicated.
 E. Lead width dimension does not include dambar protrusion. Allowable dambar protrusion shall not cause the lead width to exceed the maximum by more than 0,08 mm. Dambar cannot be located on the lower radius or the foot. Minimum space between protrusion and an adjacent lead is 0,07 mm for 0,40-mm and 0,50-mm pitch packages.

F. This dimension is defined as the distance from the seating plane to the lowest point of the package body.

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